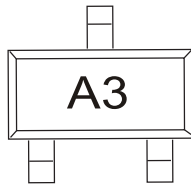


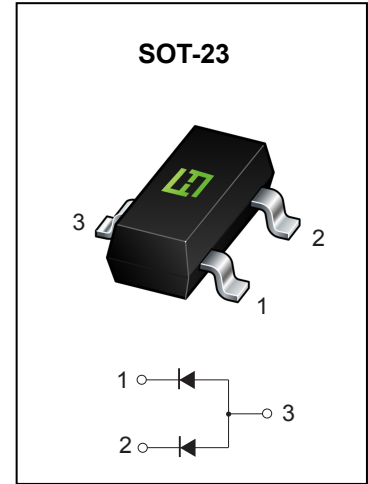
### FEATURES

- Low forward voltage
- Fast reverse recovery time

### MARKING: A3



Solid dot = Green molding compound device, if none, the normal device.



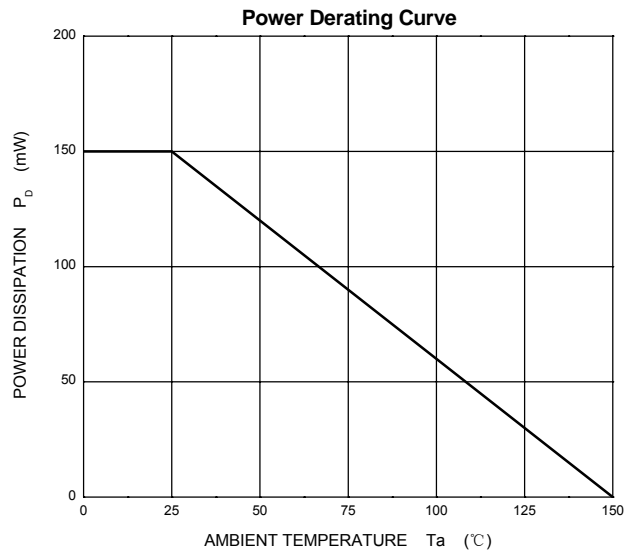
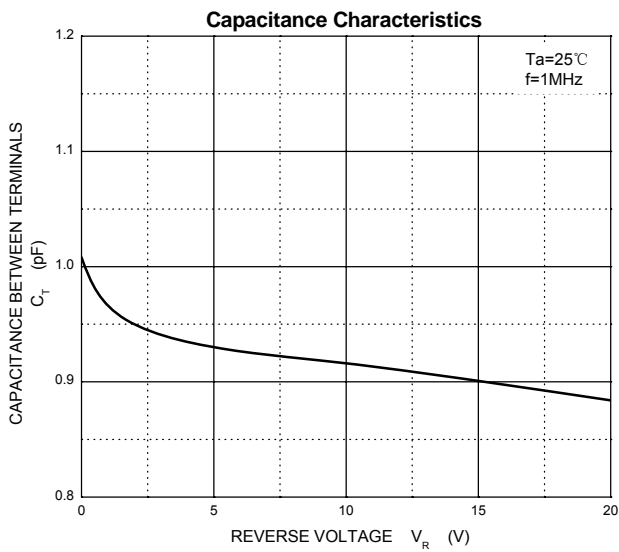
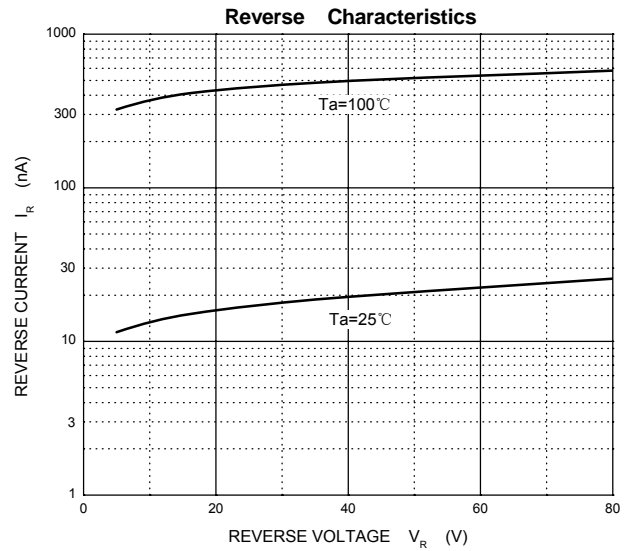
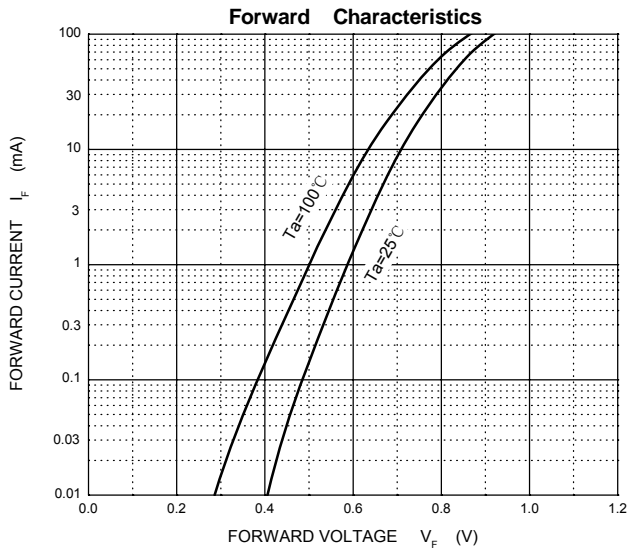
### Maximum Ratings @Ta=25°C

Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	$V_{RM}$	85	V
DC Blocking Voltage	$V_R$	80	V
Forward Continuous Current	$I_{FM}$	300	mA
Average Rectified Output Current	$I_o$	100	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	$I_{FSM}$	2.0	A
Power Dissipation	$P_D$	150	mW
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	833	°C/W
Operation Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	°C

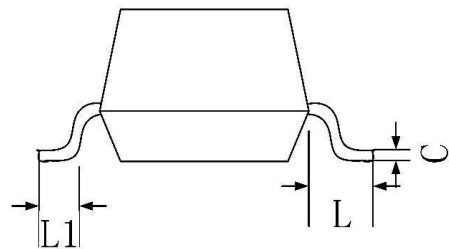
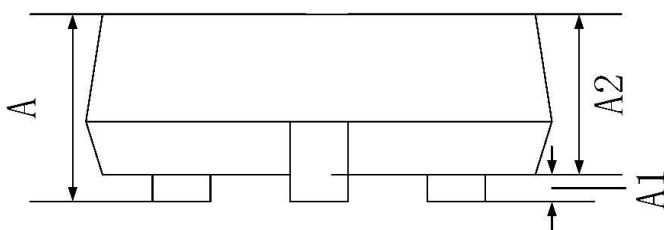
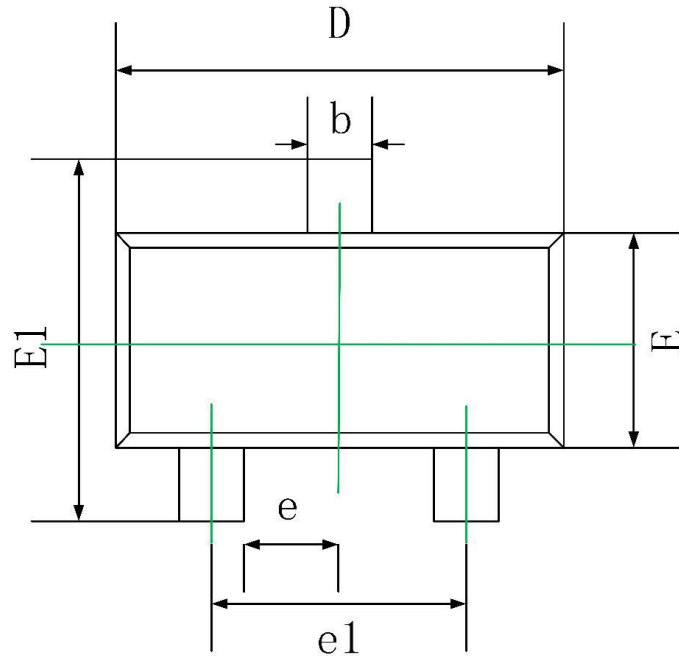
### Electrical Characteristics @Ta=25°C

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Reverse breakdown voltage	$V_{(BR)}$	80			V	$I_R=100\mu A$
Forward voltage	$V_{F1}$		0.61		V	$I_F=1mA$
	$V_{F2}$		0.74		V	$I_F=10mA$
	$V_{F3}$		0.92	1.2	V	$I_F=100mA$
Reverse current	$I_{R1}$			0.1	$\mu A$	$V_R=30V$
	$I_{R2}$			0.5	$\mu A$	$V_R=80V$
Capacitance between terminals	$C_T$		2.2	4.0	pF	$V_R=0, f=1MHz$
Reverse recovery time	$t_{rr}$		1.6	4.0	ns	$I_F=I_R=10mA, I_{rr}=0.1 \times I_R$

### Typical Characteristics



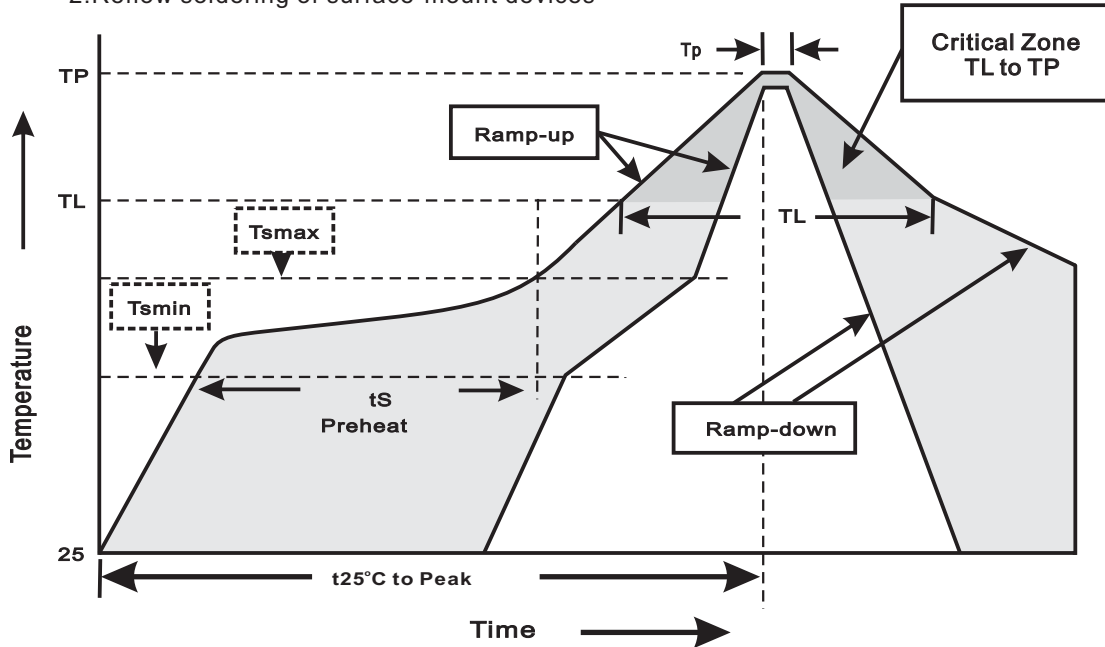
### SOT-23 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020

**Suggested thermal profiles for soldering processes**

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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